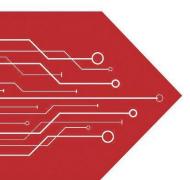
# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Product data sheet

www.msksemi.com





Cellular phones audio

MP3 players

Digital cameras

Portable applicationss

mobile telephone

#### **Features**

Small Body Outline Dimensions:

0.61 mm x 0.31 mm

Low Body Height: 0.28 mm

Low Leakage

Response Time is Typically < 1 ns

ESD Rating of Class 3 (> 16 kV) per Human Body

Model

IEC61000-4-2 Level 4 ESD Protection

These are Pb-Free Devices

We declare that the material of product

compliance with RoHS requirements.





**DFN0603** 

#### **ELECTRICAL CHARACTERISTICS**

P/N	V <sub>RWM</sub>	I <sub>R1</sub> (μΑ) @ V <sub>RWM</sub>	I <sub>R2</sub> (μ <b>A</b> ) @ V <sub>R</sub> =5∨		/) @ I <sub>T</sub> te 2)	lτ	Vc (V) @ I <sub>PP</sub> = 1 A (Note 3)		IPP(A)	<b>Ррк(W)</b> (Note 3)	C (pF)
1710	Max	Max	Max	Min	Max	mA	Max	Max	Max	Max	Max
ESD05V02D-MS	5.0	0.5	1	5.6	9.5	1.0	7.5	9.5	5	40	10

Other voltage available upon request.

 $V_{BR}$  is measured with a pulse test current IT at an ambient temperature of 25  $^{\circ}\mathrm{C}$ 

Surge current waveform per Figure 3.

#### **MAXIMUM RATINGS**

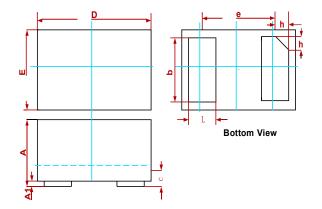
Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge Contact discharge		±25 ±20	kV kV
ESD Voltage Per Human Body Model		16	kV
Total Power Dissipation on FR-5 Board (Note 1)	PD	200	mW
<b>@</b> T <sub>A</sub> =25℃			
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	Ç
Lead Solder Temperature – Maximum (10	TL	260	$^{\circ}$
Second Duration)			

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0\*0.75\*0.62 in.

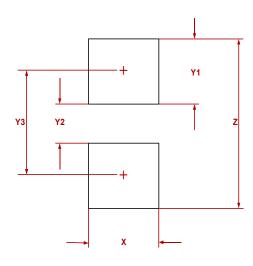


## **PACKAGE MECHANICAL DATA**



	DIMENSIONS					
	MILLIMETERS					
SYM	MIN	NOM		MAX		
Α	0.230			0.330		
A1	0.000	0.020		0.050		
b	0.215	0.245		0.275		
С	0.120	0.150		0.180		
D	0.550	0.600		0.650		
е	0.355 BSC					
Е	0.250	0.300		0.350		
L	0.160	0.190		0.220		
h	0.079 BSC					

## **Suggested Pad Layout**



SYM	DIMENSIONS				
STIVI	MILLIMETERS	INCHES			
Х	0.30	0.012			
Y1	0.25	0.010			
Y2	0.15	0.006			
Y3	0.40	0.016			
Z	0.65	0.026			

## **REEL SPECIFICATION**

P/N	PKG	QTY
ESD05V02D-MS	DFN0603	10000



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